



**IEEE EMC Society
Technical Committee 4 – EMI Control**

<http://www.ewh.ieee.org/soc/emcs/committees/tc04/index.html>

Meeting Minutes

Place: Raleigh Convention Center, Raleigh, NC, USA

Date: 05 August 2014

1 Welcome & Introductions

The meeting called to order at 1100 by Phil Berger, TC 4 Chair. Attendees introduced themselves.

John Kraemer, TC 4 Vice-Chair, read the TC 4 Charter and described the purpose of the TC and the requirements for membership.

2 Sign In Sheet

The attendance sheet was passed around for signature. Attendees wishing to become members were requested to provide a short biography and a resume.

3 Review of Draft Agenda

The draft agenda was reviewed and approved.

4 Announcements

None.

5 Last Meeting's Minutes

Minutes from the 2013 meeting in Denver, CO, USA were reviewed and accepted without changes.

6 Secretary's Report

Ross. Carlton, TC 4 Secretary, reviewed the status of the Committee membership. At the 2013 meeting, the Committee had 27 attendees.

The TC 4 website has been updated with the latest information and made consistent with the sites of other TCs. In addition, TC 4 has created a LinkedIn group to facilitate communications and coordination. The LinkedIn group currently has 42 members – up from 37 members in 2013.

7 New Business

7.1 TC Officer Elections

The TC elects officers every two (2) years. The current officers have served two (2) years of their two year term. As a result, officer elections were held. The voting of the TC confirmed the current officers for an additional two (2) year term. The current officers are:

Chairman: Phil Berger
Vice-Chairman: John Kraemer
Secretary: Ross Carlton

The next officer elections will be held in 2016 at the EMC Symposium in Ottawa, Canada.

7.2 TAC Performance Guidelines for TCs

Mr. Berger reviewed the new performance guidelines for EMCS TCs. In the previous period, the TC scored a total of 27 points (the minimum acceptable performance is 8 points). The good score was mainly driven by the number of technical papers reviewed and the acceptance of TC-sponsored workshops and tutorials.

7.3 2014 Symposium Activities

Mr. Berger reviewed the TC's activities in support of the 2014 IEEE EMC Symposium. The TC supported the Symposium in the following ways:

- Chaired three Technical Sessions.
- Sponsored one half-day Workshop on "System Level Approaches to Design and Test for EMI Control". An additional workshop was proposed but not accepted.
- Reviewed 22 technical papers with 21 accepted.

7.4 Program of Work Discussion

Mr. Berger solicited the attendees for proposals on future work by the TC.

Mark Montrose began with a discussion of workshops/tutorials submitted to the 2014 EMC Symposium. The submission of the workshop on the topic of EMC properties of materials was rejected without constructive feedback. Discussion ensued of the process of the submission and approval of TC-sponsored content.

ACTION: Mr. Carlton will contact the Workshops & Tutorials Chair to request the scoring data and send it to the TC.

Gary Fenical raised the topic of EMI gasket performance characterization work. Mr. Fenical provided an overview of the state of current EMI gasket test methods and the need for revisions to existing methods where possible and to create new methods where needed. Overall interest in

the topic is low. It was noted that work is in progress on a revision of P1302. After group discussion, Mr. Kraemer recommended supporting the P1302 work instead of focusing on a new standard. There was general agreement from the TC membership. Davy Pissoort noted that a PAR has been approved to revise P1302 in order to increase the maximum frequency on the method to 40 GHz (currently limited to 18 GHz). Mr. Pissoort issued an invitation to interested persons to attend a meeting on Thursday at 2pm. Mr. Fenical among others will participate. As a result of these decisions, Mr. Kraemer motioned to close subcommittee 4 in favor of TC 4 members engaging directly in the P1302 revision effort. The motion received unanimous approval.

David Green presented on “The Reflection Myth”, regarding near field (small enclosure, direct PCB application) EMI gasket characterization and specification. The lack of a reliable characterization method for near field and the inconsistency in manufacturer data sheets indicates that a new method may be required. Mr. Green is seeking input on the need and interest in developing a method to quantify NF absorber performance. The TC members provided feedback and offered several paths for moving forward, including participating in the revision of P1302.

7.5 EMC Symposium 2015 plans

7.5.1 Santa Clara, 15-21 March 2015

7.5.1.1 TC-4 Meeting

TC-4 will hold its next meeting at the Symposium.

7.5.1.2 Workshops & Tutorials

The TC proposes to sponsor three ½-day workshops or tutorials. The general topic and the session organizer are as follows:

- Properties of Materials for EMI Control – Mr. Montrose
- RF absorber characterization and use in small enclosures – Mr. Green
- Troubleshooting EMI Failures – Mr. Carlton

7.5.1.3 Special Sessions

The TC does not have any plans to propose a special session at this time.

7.5.2 Dresden, 16-22 August 2015

7.5.2.1 TC-4 Meeting

TC-4 will hold a meeting at the Symposium.

7.5.2.2 Workshops & Tutorials

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- Properties of Materials for EMI Control – Mr. Montrose



- RF absorber characterization and use in small enclosures – Mr. Green
- Troubleshooting EMI Failures – Mr. Carlton

7.5.2.3 Special Sessions

The TC does not have any plans to propose a special session at this time.

7.5.3 Technical Paper Reviews

The TC will review technical papers for inclusion in the 2014 Symposium. At least three reviews are required for each submitted paper. The TC leadership will identify reviewers, make review assignments, and collect all comments.

8 Old Business

None

9 Action Items

None

10 Closing

The meeting was adjourned at 1230.

Minutes submitted by: Ross Carlton, Secretary, TC4 (ross.carlton@ieee.org)

TC4 Member List

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